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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/944,732	08/31/2001	Lee John Smith	M-11443 US	2003
22888 7	590 03/03/2004		EXAM	INER
BEVER HOFFMAN & HARMS, LLP TRI-VALLEY OFFICE 1432 CONCANNON BLVD., BLDG. G			GRAYBILL	, DAVID E
			ART UNIT	PAPER NUMBER
LIVERMORE, CA 94550			2827	

DATE MAILED: 03/03/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Annicontico
	Application No.	Applicant(s)
Office Action Summary	09/944,732	SMITH ET AL.
Office Action Summary	Examiner	Art Unit
The MAILING DATE of this communication	David E Graybill	2827
Period for Reply	on appears on the cover sneet wi	un the correspondence address
A SHORTENED STATUTORY PERIOD FOR F THE MAILING DATE OF THIS COMMUNICAT - Extensions of time may be available under the provisions of 37 C after SIX (6) MONTHS from the mailing date of this communicati - If the period for reply specified above is less than thirty (30) days - If NO period for reply is specified above, the maximum statutory - Failure to reply within the set or extended period for reply will, by Any reply received by the Office later than three months after the earned patent term adjustment. See 37 CFR 1.704(b).	ION. CFR 1.136(a). In no event, however, may a resion. s, a reply within the statutory minimum of thirt period will apply and will expire SIX (6) MON a statute, cause the application to become AB	eply be timely filed y (30) days will be considered timely. THS from the mailing date of this communication. ANDONED (35 U.S.C. § 133).
Status		
1) ☐ Responsive to communication(s) filed on 2a) ☐ This action is FINAL . 2b) ☐ 3) ☐ Since this application is in condition for a closed in accordance with the practice units.	This action is non-final. Ilowance except for formal matt	
Disposition of Claims		
4) ☐ Claim(s) 26-34 is/are pending in the applied 4a) Of the above claim(s) is/are with 5) ☐ Claim(s) is/are allowed. 6) ☐ Claim(s) 26-34 is/are rejected. 7) ☐ Claim(s) is/are objected to. 8) ☐ Claim(s) are subject to restriction are	thdrawn from consideration.	
Application Papers		
9)☐ The specification is objected to by the Exact 10)☑ The drawing(s) filed on <u>03 December 200</u> Applicant may not request that any objection to Replacement drawing sheet(s) including the control of the oath or declaration is objected to by the specific	0.1 is/are: a) \square accepted or b) \square to the drawing(s) be held in abeyan correction is required if the drawing(ce. See 37 CFR 1.85(a). s) is objected to. See 37 CFR 1.121(d).
Priority under 35 U.S.C. § 119		
12) Acknowledgment is made of a claim for for a) All b) Some * c) None of: 1. Certified copies of the priority docu 2. Certified copies of the priority docu 3. Copies of the certified copies of the application from the International B * See the attached detailed Office action for	ments have been received. Iments have been received in A e priority documents have been Bureau (PCT Rule 17.2(a)).	pplication No received in this National Stage
Attachment(s) 1) X Notice of References Cited (PTO-892)	4) ⊠ Interview S	ummary (PTO-413) _{1 (-2}
 Notice of Draftsperson's Patent Drawing Review (PTO-943) Information Disclosure Statement(s) (PTO-1449 or PTO/5 Paper No(s)/Mail Date 		ummary (PTO-413))/Mail Date. 山かりがりはいかり formal Patent Application (PTO-152)

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Applicant's election without traverse of the species of Figure 3, in the paper filed on 12-8-3 is acknowledged. However, applicant's indication that claims 25-35 are readable thereon is incorrect; instead, claims 26-34 are readable thereon.

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 26-34 are rejected under 35 U.S.C. 102(e) as being anticipated by Shin (2004/0007771).

The applied reference has a common assignee with the instant application. Based upon the earlier effective U.S. filing date of the reference, it constitutes prior art under 35 U.S.C. 102(e). This rejection under 35 U.S.C. 102(e) might be overcome either by a showing under 37 CFR 1.132 that any invention disclosed but not claimed in the reference was derived from the inventor of this application and is thus not the invention "by another," or by an appropriate showing under 37 CFR 1.131.

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In the abstract, and at paragraphs 24, 30, 35-37, 64-71, 110-114, and claims 8-10, Shin discloses the following:

A semiconductor package comprising: a substrate 10 having opposing first and second surfaces and through hole 14 extending through the substrate between the first and second surfaces; a first conductive circuit pattern 19 disposed on the first surface of the substrate, and a second conductive pattern 19 disposed on the second surface of the substrate, wherein the first conductive circuit pattern includes at least "bond fingers" (illustrated but not labeled) and lands 13, the second conductive pattern includes at least lands 13, and at least some of the first and second circuit patterns are electrically coupled 14 through the substrate; a first semiconductor chip 2 having opposed active and inactive surfaces, wherein the first semiconductor chip is disposed within the through hole without contacting the substrate, and the active surface of the first semiconductor chip includes bond pads 2a; a second semiconductor chip 1 having opposed active and inactive surfaces, wherein the second semiconductor chip is disposed within or over the through hole without contacting the substrate, and the active surface of the second semiconductor chip includes bond pads 1a, wherein the inactive surface of the second semiconductor chip faces and is mounted on the active surface of the first semiconductor chip so that the active surfaces of the first and second semiconductor chips are oriented in a Art Unit: 2827

same direction; a plurality of first conductive wires 20, wherein each of the first conductive wires electrically connects a respective one of the bond pads of the first semiconductor chip to a respective one of the bond fingers of the first conductive circuit pattern; a plurality of second conductive wires 20, wherein each of the second conductive wires electrically connects a respective one of the bond pads of the second semiconductor chip to a respective one of the bond fingers of the first conductive circuit pattern; and an encapsulant 30 filling the through hole and contacting the first surface of the substrate, the bond fingers of the first conductive circuit pattern, the first semiconductor chip, the second semiconductor chip, and the first and second conductive wires, wherein the inactive surface of the first semiconductor chip is exposed through the encapsulant in a common plane with the second surface of the substrate ("the second surface of the substrate and the inactive surface of the second semiconductor chip being in a common horizontal plane"), and the lands of the first and second conductive circuit patterns are uncovered by the encapsulant; wherein the inactive surface of the second semiconductor chip has a smaller area than the active surface of the first semiconductor chip; wherein the first and second semiconductor chips are a same size; a plurality of conductive balls 40, wherein each of the conductive balls is fused to a respective one of the lands of the second conductive circuit pattern, and the active surfaces of the

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first and second semiconductor dies are oriented in a same direction as the first surface of the substrate; wherein each of the conductive balls is fused to a respective one of the lands of the first conductive circuit pattern, and the active surfaces of the first and second semiconductor dies are oriented in a same direction as the first surface of the substrate.

The art made of record and not applied to the rejection is considered pertinent to applicant's disclosure. It is cited primarily to show inventions similar to the instant invention.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Any telephone inquiry of a general nature or relating to the status (MPEP 203.08) of this application or proceeding should be directed to Group 2800 Customer Service whose telephone number is 571-272-2815.

Any telephone inquiry concerning this communication or earlier communications from the examiner should be directed to David E. Graybill at (571) 272-1930. Regular office hours: Monday through Friday, 8:30 a.m. to 6:00 p.m.

The fax phone number for group 2800 is (703) 872-9306.

David E. Graybill
Primary Examiner

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